

BRCM24C32SC



DATA SHEET

BRCM24C32SC SOP-8 32 Kbit I²C

1.7V	2.5~5.5V	1Mhz	1.7~2.5V
400Khz			
CMOS	400uA	1.6mA	

/ Pinning

Pin	Name	Type	Description
1	E0	Input	
2	E1	Input	
3	E2	Input	
4	GND	Ground	
5	SDA	I/O	/
6	SCL	Input	
7	WCB	Input	
8	VCC	Power	

/ Marking

/ Absolute Maximum Ratings(Ta=25)

/ Reliability Characteristic

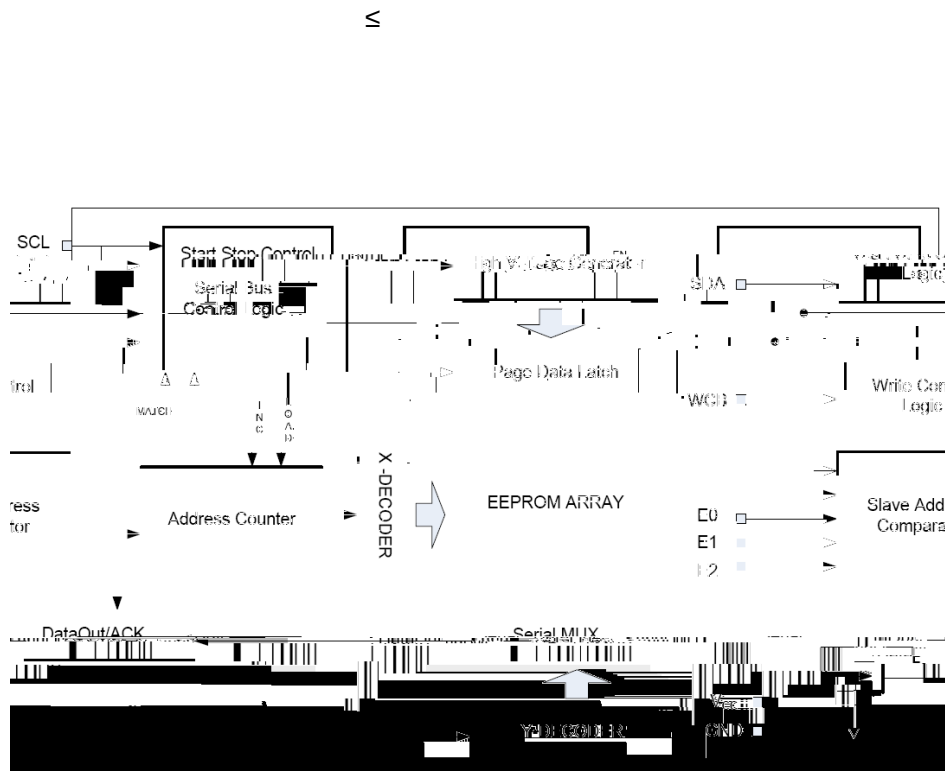
BRCM24C32SC



DATA SHEET

1.7V to 5.5V,

$T_A = -40^{\circ}\text{C}$ to 85

[illegible]

/ Functional Description

/ Data Input

SDA

SDA

SCL

(1) SCL

SDA

(1)

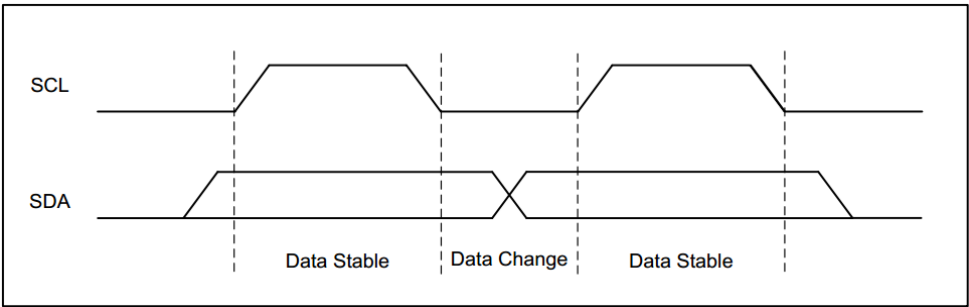


Figure 1 Data Validity

/ Start Condition

SCL

SDA

2

/ Stop Condition

SCL

SDA

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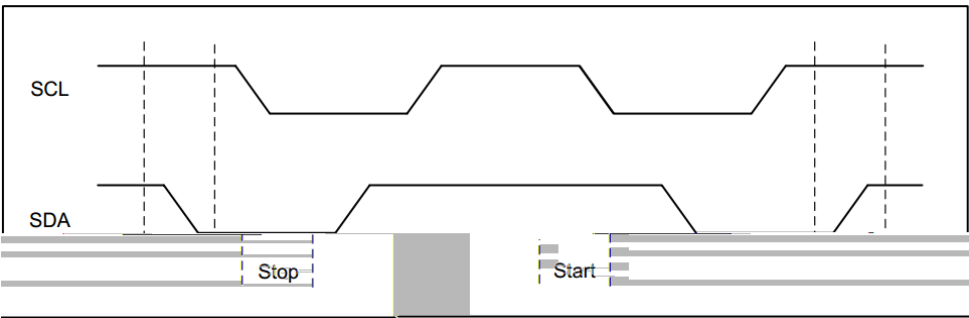


Figure 2 Start and Stop Definition

ACK / Acknowledge

ACK

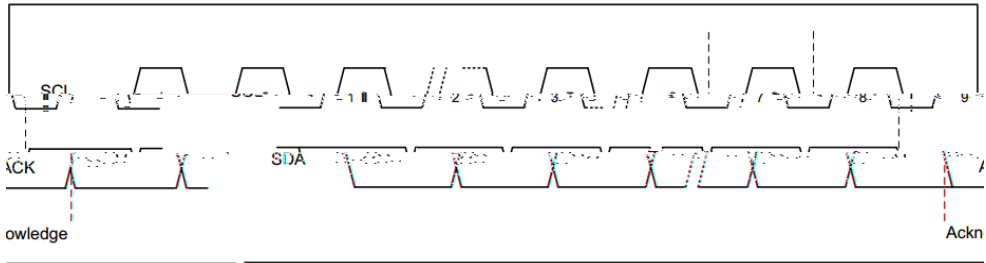
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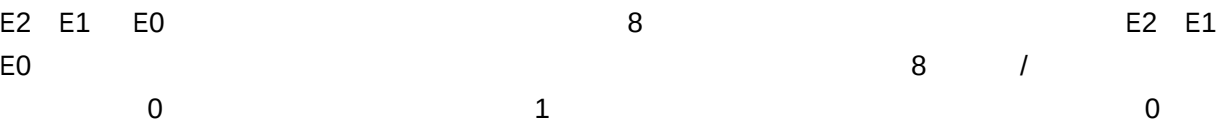
" 0 "

9

/ Functional Description



/ Functional Description



/ Data Security

BRCM24C32SC WCB Vcc

/ Byte Write



/ Functional Description

/ Acknowledge Polling

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/ Functional Description

/ Read Operations

/ “ 1 ”

;

/ Current Address Read

1

/ “ 1 ”

“ 0 ”

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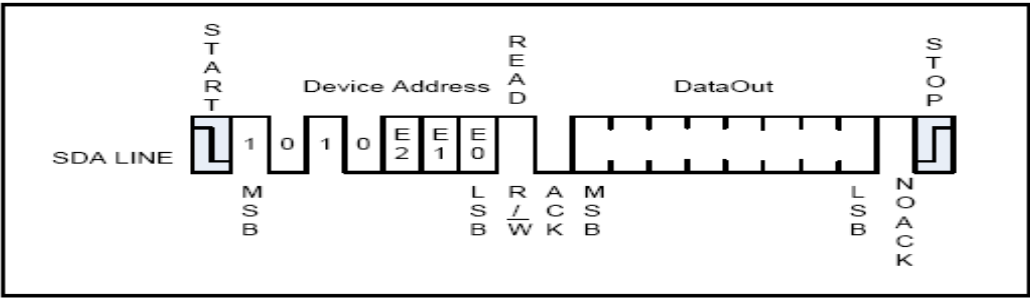


Figure 7

/ Random Address Read

“ ”

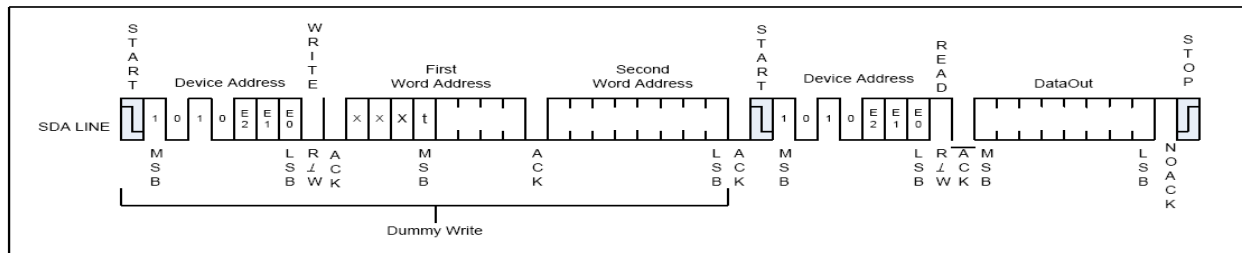
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“ 0 ”

8

/ Functional Description



Notes: [1] x means don't care bits.

[2] t means don't care bit for BRCM24C32SC

Figure 8 Random Address Read

/ Sequential Read

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“ 0 ”

9

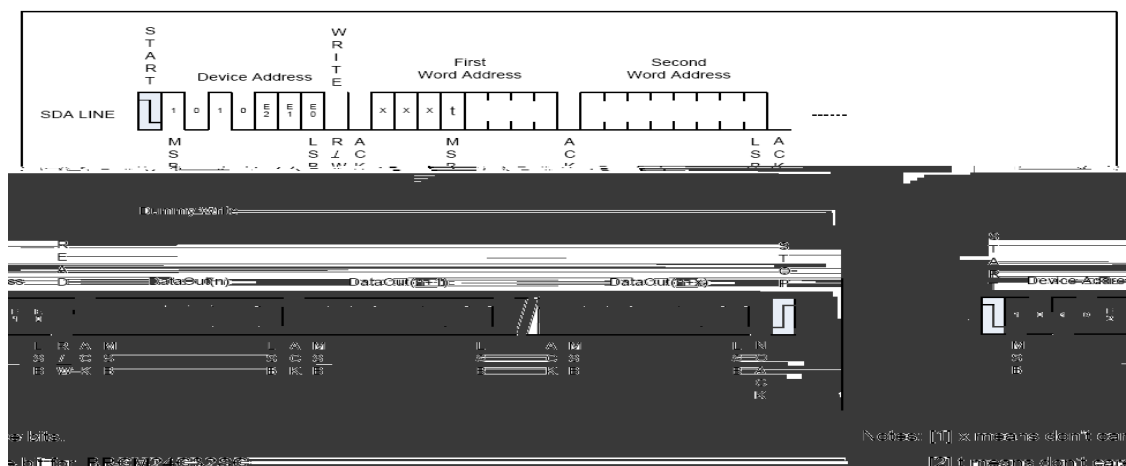


Figure 9

/ Functional Description

/ Read Identification Page

32				
1011b	A15 / A5	A4 / A0	ID	ID
		10d	22	
32				

/ Read the Lock Status

[ACK +] / NoACK,(10)

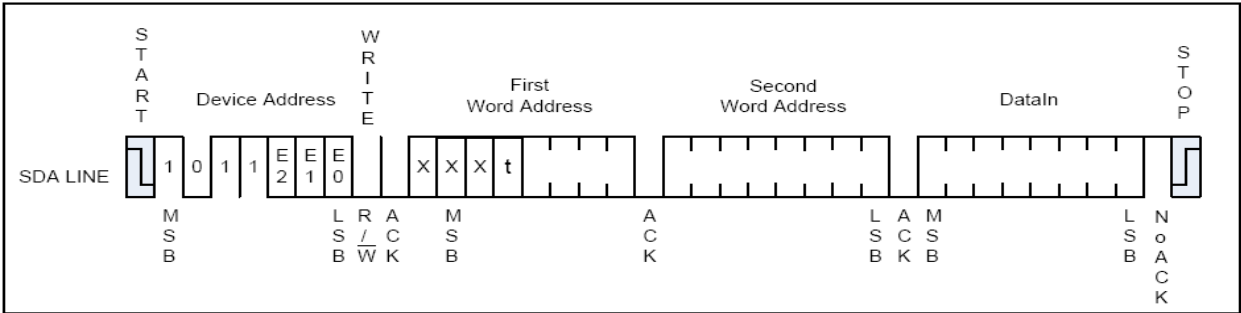


Figure 10 Lock Status Read (When Identification page locked, return NoACK after one data byte)

/ Read Serial Number

EEPROM 1 128 “ ” EEPROM 1

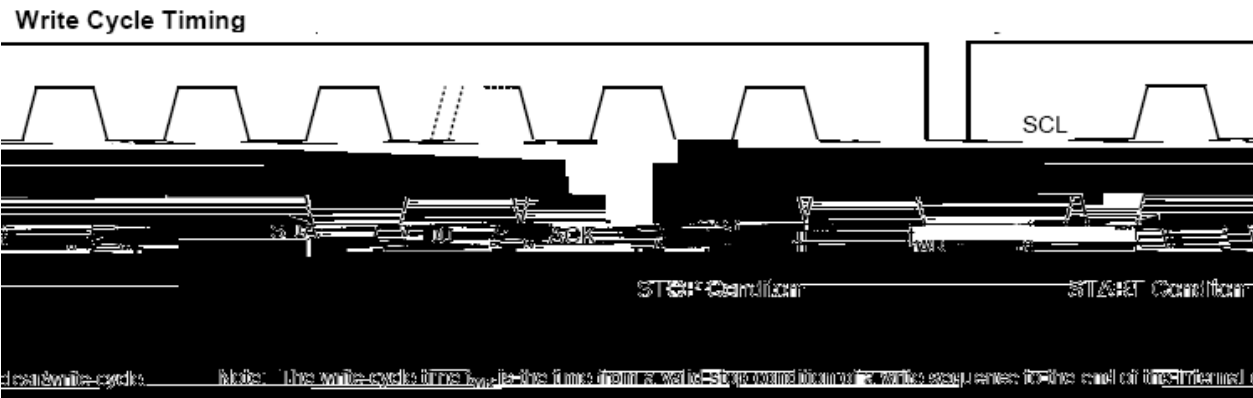
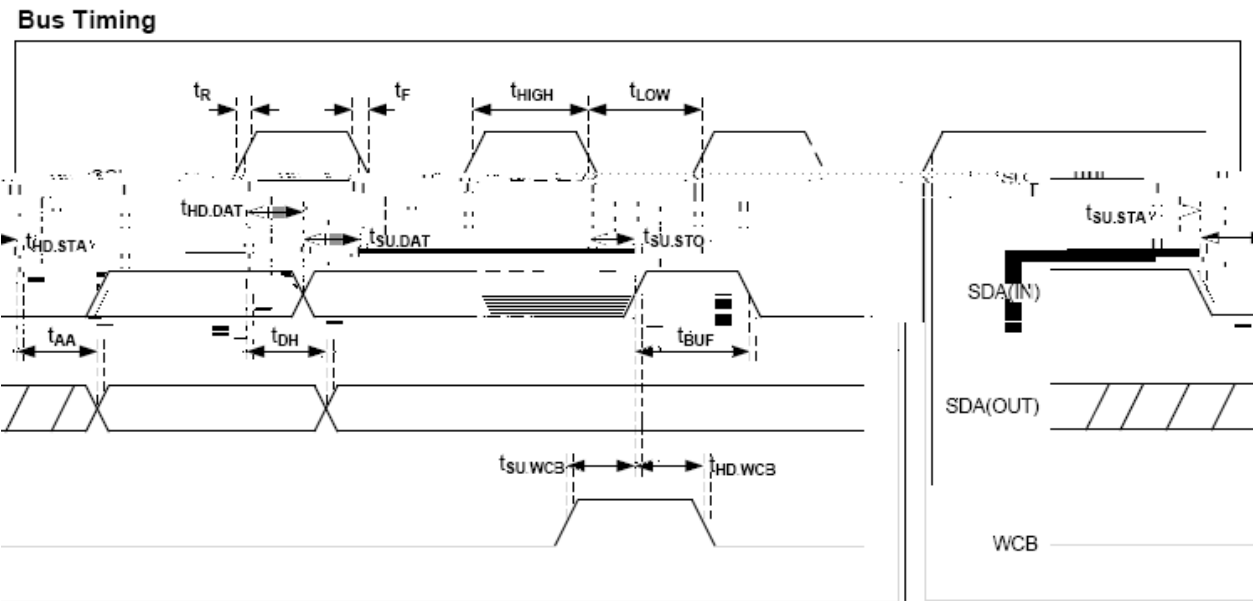
/ Functional Description

	A11	A10	" 10 "	2	" 10 "
	0800h				
128	16				
	128				ACK
	11				



Figure 11 Sequential Read

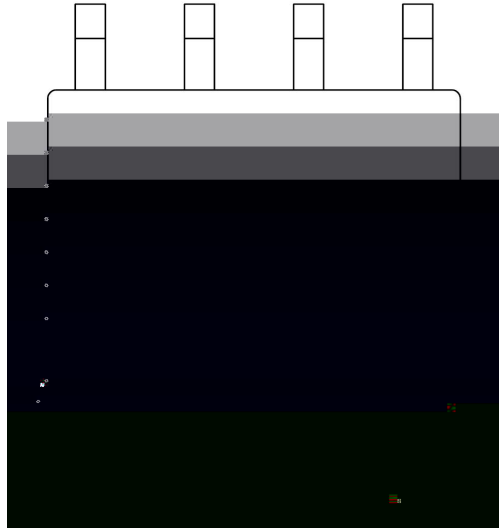
/ Time Sequence Diagram



/ Package Dimensions

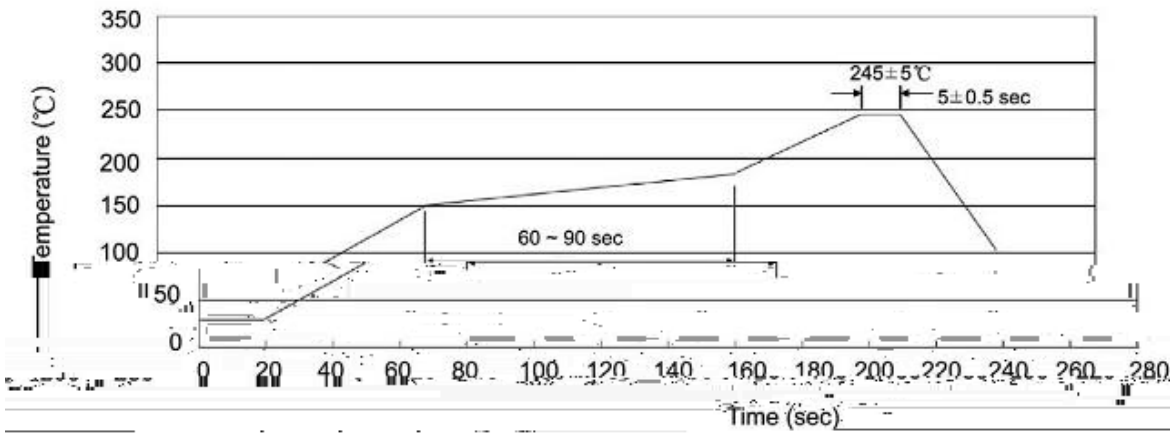


/ Marking Instructions



24C32

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ± ± ±

/ Packaging SPEC.

封装形式	包装数量					包装尺寸		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOP/ESOP-8	4,000	2	8,000	6	48,000	13 ×12	360×360×50	380×335×366